

Fig.	Tension d'isolement	Rapport de transfert de courant - Type (%)			V _{CEO} (max.)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
		(Min.)	Typique	(max.)				1	10	100
16	2500	400	1100	—	—	SMD	6N139SDTR-ND0	371.39	1.00	—
	2500	400	—	7000	—	SOIC	FOD073LR1CT-ND0	4.02	3.36	2.44
	2500	400	—	7000	—	SOIC	FOD073LR1TR-ND0	—	884.27	500
17	5000	50	—	100	70	SMD	FOD2743ASDVCT-ND0	1.52	1.22	.85
	5000	50	—	100	70	SMD	FOD2743ASDVTR-ND0	—	474.32	1,000
	5000	50	—	100	70	SMD	FOD2743BSDVCT-ND0	1.11	.89	.62
	5000	50	—	100	70	SMD	FOD2743BSDVTR-ND0	—	343.88	1,000
	5000	50	—	100	70	SMD	FOD2743CSDVCT-ND0	1.07	.86	.60
	5000	50	—	100	70	SMD	FOD2743CSDVTR-ND0	—	332.02	1,000
18	5000	100	—	200	30	DIP	FOD2711TV-ND0	.82	.64	.46
	2500	100	—	200	30	SOIC	FOD2712R1VCT-ND0	1.22	.98	.68
	2500	100	—	200	30	SOIC	FOD2712R1VTR-ND0	—	230.38	500
	5000	100	—	200	30	SMD	FOD2741ASDVCT-ND0	1.52	1.22	.85
	5000	100	—	200	30	SMD	FOD2741ASDVTR-ND0	—	474.32	1,000
	5000	100	—	200	30	SMD	FOD2741BSDVCT-ND0	1.11	.89	.62
	5000	100	—	200	30	SMD	FOD2741BSDVTR-ND0	—	343.88	1,000
	5000	100	—	200	30	SMD	FOD2741CSDVCT-ND0	.71	.60	.48
	2500	100	140	200	70	SOIC	FOD2742AR1VCT-ND0	1.34	1.07	.75
	2500	100	140	200	70	SOIC	FOD2742AR1VTR-ND0	—	415.03	1,000
	2500	100	140	200	70	SOIC	FOD2742BR1VCT-ND0	1.03	.83	.58
	2500	100	140	200	70	SOIC	FOD2742BR1VTR-ND0	—	194.39	500
2500	100	140	200	70	SOIC	FOD2742CR1VCT-ND0	.96	.77	.53	
2500	100	140	200	70	SOIC	FOD2742CR1VTR-ND0	—	179.99	500	
19	5000	1000	4000	15000	300	DIP	FOD852-ND0	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD852S-ND0	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD852SDCT-ND0	.74	.58	.42
	5000	1000	4000	15000	300	SMD	FOD852SDTR-ND0	—	246.99	1,000
	5000	1000	4000	15000	300	DIP	FOD852W-ND0	.70	.55	.39
	5000	1000	4000	15000	300	DIP	FOD852300-ND0	.70	.55	.39
	5000	1000	4000	15000	300	DIP	FOD852300W-ND0	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD8523S-ND0	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD8523SDCT-ND0	.74	.58	.42
	5000	1000	4000	15000	300	SMD	FOD8523SDTR-ND0	—	461.04	2,000
20	2500	—	—	—	—	DIP	HCLP3700-ND0	2.91	2.59	1.67
21	2500	100	—	200	70	SMD	MOC207R1MCT-ND0	.70	.55	.39
	2500	100	—	200	70	SMD	MOC207R1MTR-ND0	—	133.83	500
	2500	100	—	200	70	SMD	MOC207R2MCT-ND0	.66	.52	.37
	2500	100	—	200	70	SMD	MOC207R2MTR-ND0	—	464.24	2,500
	2500	100	—	200	70	SOIC	MOC207R1MCT-ND0	1.07	.86	.60
	2500	100	—	200	70	SOIC	MOC207R1MTR-ND0	—	202.16	500
2500	100	—	200	70	SOIC	MOC207R2MCT-ND0	1.07	.86	.60	
2500	100	—	200	70	SOIC	MOC207R2MTR-ND0	—	790.81	2,500	
22	5000	40	—	80	70	SMD	FOD617AS-ND0	.43	.32	.21
	5000	40	—	80	70	SMD	FOD617AS-ND0	.43	.32	.21
	5000	63	—	125	70	SMD	FOD617B3SDCT-ND0	.56	.43	.28
	5000	63	—	125	70	SMD	FOD617B3SDTR-ND0	—	143.25	1,000
	7500	100	—	—	60	SMD	4N29SM-ND0	.56	.44	.32
7500	100	—	—	60	SMD	4N29SR2MCT-ND0	.65	.51	.36	
7500	100	—	—	60	SMD	4N29SR2MTR-ND0	—	196.22	1,000	
7500	100	—	—	60	SMD	4N30SM-ND0	.56	.44	.32	
7500	100	—	—	60	SMD	4N30SR2MCT-ND0	.65	.51	.36	
7500	100	—	—	60	SMD	4N30SR2MTR-ND0	—	196.22	1,000	
7500	500	—	—	60	SMD	4N32SM-ND0	.56	.44	.32	
7500	20	—	—	80	SMD	4N38SR2MCT-ND0	.91	.71	.51	
7500	20	—	—	80	SMD	4N38SR2MTR-ND0	—	274.43	1,000	
7500	40	—	—	70	SMD	CNY17F1SM-ND0	.50	.40	.29	
7500	300	—	—	30	SMD	H11AG1SM-ND0	.90	.71	.51	
7500	300	—	—	30	SMD	H11AG1SR2MCT-ND0	.99	.80	.56	
7500	300	—	—	30	SMD	H11AG1SR2MTR-ND0	—	308.64	1,000	
7500	500	—	—	60	SMD	H11B1SM-ND0	.56	.44	.32	
7500	500	—	—	60	SMD	H11B1SR2MCT-ND0	.65	.51	.36	
7500	500	—	—	60	SMD	H11B1SR2MTR-ND0	—	196.22	1,000	
7500	500	—	—	60	SMD	H11B1SR2VMCT-ND0	.65	.51	.36	
7500	500	—	—	60	SMD	H11B1SR2VMTR-ND0	—	196.22	1,000	
7500	20	—	—	300	SMD	H11D1SM-ND0	.77	.61	.43	
7500	20	—	—	300	SMD	H11D1SR2MCT-ND0	.91	.71	.51	
7500	20	—	—	300	SMD	H11D1SR2MTR-ND0	—	274.43	1,000	
7500	20	—	—	300	SMD	H11D1SR2VMCT-ND0	.91	.71	.51	
7500	20	—	—	300	SMD	H11D1SR2VMTR-ND0	—	274.43	1,000	
7500	20	—	—	300	SMD	H11D2SR2MCT-ND0	.91	.71	.51	
7500	20	—	—	300	SMD	H11D2SR2MTR-ND0	—	274.43	1,000	
7500	20	—	—	300	SMD	H11D2SR2VMCT-ND0	.91	.71	.51	
7500	20	—	—	300	SMD	H11D2SR2VMTR-ND0	—	274.43	1,000	
7500	20	—	—	200	SMD	H11D3SM-ND0	.77	.61	.43	
7500	20	—	—	200	SMD	H11D3SR2MCT-ND0	.91	.71	.51	
7500	20	—	—	200	SMD	H11D3SR2MTR-ND0	—	274.43	1,000	
7500	—	—	200	30	SMD	H11F1SM-ND0	2.43	2.16	1.40	
7500	—	—	200	30	SMD	H11F1SR2MCT-ND0	2.68	2.40	1.55	
7500	—	—	200	30	SMD	H11F1SR2MTR-ND0	—	968.50	1,000	
7500	—	—	470	15	SMD	H11F3SM-ND0	2.43	2.16	1.40	
7500	—	—	470	15	SMD	H11F3SR2MCT-ND0	2.68	2.40	1.55	
7500	—	—	470	15	SMD	H11F3SR2MTR-ND0	—	968.50	1,000	
7500	—	—	470	15	SMD	H11F3SR2VMCT-ND0	2.68	2.40	1.55	
7500	—	—	470	15	SMD	H11F3SR2VMTR-ND0	—	968.50	1,000	
7500	1000	—	—	100	SMD	H11G1SM-ND0	.78	.61	.44	
7500	1000	—	—	100	SMD	H11G1SR2MCT-ND0	.92	.71	.51	
7500	1000	—	—	100	SMD	H11G1SR2MTR-ND0	—	275.80	1,000	
7500	500	—	—	80	SMD	H11G2SM-ND0	.78	.61	.44	
7500	500	—	—	80	SMD	H11G2SR2MCT-ND0	.92	.71	.51	
7500	500	—	—	80	SMD	H11G2SR2MTR-ND0	—	275.80	1,000	
7500	200	—	—	55	SMD	H11G3SR2MCT-ND0	.93	.72	.52	
7500	200	—	—	55	SMD	H11G3SR2MTR-ND0	—	279.92	1,000	
7500	120	—	—	100	SMD	MCT5201SM-ND0	.90	.71	.51	
7500	120	—	—	100	SMD	MCT5201SR2MCT-ND0	.99	.80	.56	
7500	120	—	—	100	SMD	MCT5201SR2MTR-ND0	—	308.64	1,000	
7500	60	—	—	100	SMD	MCT5210SM-ND0	.90	.71	.51	
7500	100	—	—	100	SMD	MCT5211SR2MCT-ND0	1.02	.82	.57	
7500	100	—	—	100	SMD	MCT5211SR2MTR-ND0	—	318.89	1,000	
7500	1.000	—	—	100	SMD	MOC8021SR2MCT-ND0	.85	.66	.47	
7500	1.000	—	—	100	SMD	MOC8021SR2MTR-ND0	—	255.22	1,000	
7500	500	—	—	100	SMD	MOC8050SR2MCT-ND0	.92	.71	.51	
7500	500	—	—	100	SMD	MOC8050SR2MTR-ND0	—	275.80	1,000	
7500	20	—	—	400	SMD	MOC8204SM-ND0	1.22	1.00	.69	

Fig.	Tension d'isolement	Rapport de transfert de courant - Type (%)			V _{CEO} (max.)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
		(Min.)	Typique	(max.)				1	10	100
23	7500	20	—	—	400	SMD	MOC8204SR2MCT-ND0	1.42	1.14	.80
	7500	20	—	—	400	SMD	MOC8204SR2MTR-ND0	—	443.11	1,000
	7500	300	—	—	60	SMD	TIL113SM-ND0	.62	.48	.35
24	7500	100	—	—	60	DIP	4N29M-ND0	.56	.44	.32
	7500	100	—	—	60	DIP	4N30M-ND0	.56	.44	.32
	7500	500	—	—	60	DIP	4N32M-ND0	.56	.44	.32
	7500	500	—	—	60	DIP	4N32VM-ND0	.56	.44	.32
	7500	500	—	—	60	DIP	4N33M-ND0	.51	.40	.29
	7500	500	—	—	60	DIP	4N33VM-ND0	.56	.44	.32
	7500	20	—	—	80	DIP	4N38M-ND0	.77	.61	.43
	7500	300	—	—	30	DIP	H11AG1M-ND0	.90	.71	.51
	7500	300	—	—	30	DIP	H11AG1VM-ND0	.90	.71	.51
	7500	500	—	—	60	DIP	H11B1M-ND0	.56	.44	.32
	7500	500	—	—	60	DIP	H11B1VM-ND0	.56	.44	.32
	7500	20	—							

Opto-isolateurs de sortie RCS et Triac (suite)



Fig.	Tension d'isolement	Déclencheur Max I _F (mA)	Tension de blocage minimale	IORM max.	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
31	3750	60	250	100nA	MFP	FODM3011R1_NF098CT-ND‡	.74	.58	.42
	3750	60	250	100nA	MFP	FODM3011R1_NF098TR-ND◊	156.42/500		
	3750	60	250	100nA	MFP	FODM3012R1_NF098CT-ND‡	.84	.66	.47
	3750	60	250	100nA	MFP	FODM3012R1_NF098TR-ND◊	177.28/500		
	3750	60	600	100nA	MFP	FODM3052R1_NF098CT-ND‡	1.10	.90	.62
	3750	60	600	100nA	MFP	FODM3052R1_NF098TR-ND◊	233.26/500		
32	3750	60	600	100nA	MFP	FODM3053R1_NF098CT-ND‡	1.19	.97	.67
	3750	60	600	100nA	MFP	FODM3053R1_NF098TR-ND◊	251.92/500		
	3750	60	600	500nA	MFP	FODM3062-ND	1.53	1.25	.87
	3750	60	600	500nA	MFP	FODM3063-ND	1.69	1.37	.95
	3750	60	800	500nA	MFP	FODM3082-ND	1.92	1.71	1.10
	3750	60	800	500nA	MFP	FODM3083-ND	1.98	1.76	1.14
36	7500	60	5300	100nA	SMD	MOC3021SR2MCT-ND	.78	.60	.43
	7500	60	5300	100nA	SMD	MOC3021SR2MTR-ND	233.26/1,000		
	7500	60	5300	100nA	SMD	MOC3023SR2MCT-ND	.78	.61	.44
	7500	60	5300	100nA	SMD	MOC3023SR2MTR-ND	234.64/1,000		
	7500	60	5300	100nA	SMD	MOC3052SM-ND	.88	.72	.50
	7500	60	5300	100nA	SMD	MOC3052SR2MCT-ND	1.05	.81	.58
37	7500	60	5300	100nA	SMD	MOC3052SR2MTR-ND	315.59/1,000		
	7500	60	5300	100nA	DIP	MOC3052TVM-ND	.88	.72	.50
	7500	60	5300	100nA	SMD	MOC3043SM-ND	1.02	.84	.58
	7500	60	5300	500nA	DIP	MOC3063TVM-ND	1.17	.96	.66
	7500	60	5300	500nA	SMD	MOC3083SR2MCT-ND	1.48	1.19	.83
	7500	60	5300	500nA	SMD	MOC3083SR2MTR-ND	461.04/1,000		

† Approbation VDE ▲ Écartement entre les broches : 0.4" ‡ Bande coupée ◊ Bande et bobine

Pièces d'accouplement à 4 broches



Fig.	Tension	Rapport de transfert de courant	V _{CEO} (max.)	tpassant/bloqué typ. (µsec.)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
14A	2500	50-600%	80	3/3	MFP	HMHAA281-ND‡	.42	.34	.26
	5000	40-80%	70	4/3	DIP	FOD617A-ND‡	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B-ND‡	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C-ND‡	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617D-ND‡	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617E-ND‡	.43	.32	.21
14B	5000	40-80%	70	4/3	DIP	FOD617A300-ND‡	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B300-ND‡	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C300-ND‡	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617D300-ND‡	.43	.32	.21
	5000	20-300%	70	4/3	DIP	FOD814-ND	.48	.38	.28
	5000	20-300%	70	4/3	SMD	FOD814S-ND	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD814SDCT-ND‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD814SDTR-ND◊	329.31/2,000		
	5000	20-300%	70	4/3	DIP	FOD814W-ND▲	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300-ND‡	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300W-ND‡▲	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143S-ND‡	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143SDCT-ND‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD8143SDTR-ND◊	329.31/2,000		
	5000	50-150%	70	4/3	DIP	FOD814A-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814AS-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814ASDCT-ND‡	.55	.43	.31
	5000	50-150%	70	4/3	SMD	FOD814ASDTR-ND◊	182.22/1,000		
5000	50-150%	70	4/3	DIP	FOD814AW-ND▲	.47	.38	.27	
5000	50-150%	70	4/3	DIP	FOD814A300-ND‡	.44	.35	.25	
5000	50-150%	70	4/3	DIP	FOD814A300W-ND‡▲	.48	.38	.28	
5000	50-150%	70	4/3	SMD	FOD814A3S-ND‡	.44	.35	.25	
5000	50-150%	70	4/3	SMD	FOD814A3SDCT-ND‡	.55	.43	.31	
5000	50-150%	70	4/3	SMD	FOD814A3SDTR-ND◊	182.22/1,000			
14C	2500	50-600%	7	3/3	DIP	HMHAA280R1CT-ND‡	.43	.33	.25
	2500	50-600%	7	3/3	DIP	HMHAA280R1TR-ND◊	75.89/500		
	2500	50-600%	80	3/3	MFP	HMHAA280R4VCT-ND‡	.43	.33	.25
	2500	50-600%	80	3/3	MFP	HMHAA280R4VTR-ND◊	352.35/2,500		
14D	5000	600-7500%	35	60/53	SMD	FOD816S-ND	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD816SDCT-ND‡	.60	.47	.34
	5000	600-7500%	35	60/53	SMD	FOD816SDTR-ND◊	198.93/1,000		
	5000	600-7500%	35	60/53	DIP	FOD816W-ND▲	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300-ND‡	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300W-ND‡▲	.53	.42	.30
5000	600-7500%	35	60/53	SMD	FOD8163S-ND‡	.53	.42	.30	
5000	600-7500%	35	60/53	SMD	FOD8163SDCT-ND‡	.60	.47	.34	
5000	600-7500%	35	60/53	SMD	FOD8163SDTR-ND◊	198.93/1,000			

† Approbation VDE ▲ Écartement entre les broches : 0.4" ‡ Bande coupée ◊ Bande et bobine

Fig.	Fonction	Entrée : sortie LSTTL	Configuration de sortie du débit en bauds : 15 Mo	Type de boîtier	N° de référence Digi-Key	Prix unitaire			Bande et bobine◊	
						1	10	100	Qté	Prix
26	Séparateur	TTL	Totem pôle	SMD	HCPL2630S-ND	3.13	2.80	1.82	—	—
33	Séparateur	TTL	Totem pôle	SMD	FOD0708R1CT-ND‡	3.52	2.94	2.14	500	773.73
34	Séparateur	TTL	Totem pôle	SMD	FOD0710-ND	3.37	2.70	2.10	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0720-ND	2.33	1.86	1.45	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0721-ND	2.56	2.05	1.59	—	—
35	Séparateur	TTL	Totem pôle	SMD	FOD0738R1CT-ND‡	6.88	5.73	4.17	1,000	2771.21

Fig.	Tension d'isolement	Courant I _{on} (max.) mA	ICCL (max.)	Tension de fonc. (max.) mV	Type boîtier	N° de référence Digi-Key	Prix unitaire			Prix de bande et bobine◊
							1	10	100	
36	5000	1.6	7.0	2.0	SMD	FOD2200SDVCT-ND‡	2.71	2.43	1.57	981.08
37	2500	50	13	5.5	SOIC	HCPL0600-ND	2.44	2.19	1.42	—
	3750	50	13	5.5	SOIC	HCPL0601-ND	3.00	2.69	1.74	—
	2500	50	13	7.0	SMD	6N137SDCT-ND‡	1.17	.94	.65	363.71
38	2500	—	—	—	SOIC	HCPL062N-ND	5.22	4.35	3.13	—
	3750	50	13	7.0	SOICW	HCPL0637-ND	2.41	2.13	1.38	—
	3750	—	—	—	SOICW	HCPL0638-ND	2.56	2.27	1.47	—
39	2500	—	—	—	SMD	HCPL2631SDCT-ND‡	2.43	2.18	1.41	880.46
40	5300	1.6	5	16	DIP	H11L1-MQT-ND	.88	.69	.50	—
	5300	1.6	5	16	SMD	H11L1SM-ND	.95	.74	.53	—
	7500	60	5	15	SMD	H11L1SR2MCT-ND‡	1.01	.78	.56	301.87
	7500	1.6	5	15	SMD	H11L1SR2VMCT-ND‡	.99	.79	.55	307.36
	7500	1.6	5	15	SMD	H11L1SVM-ND‡	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TM-ND	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TVM-ND‡	.95	.74	.53	—
	5300	1.6	5	16	DIP	H11L1V-MQT-ND‡	.88	.69	.49	—
	7500	1.6	5	15	DIP	H11L1VM-ND	.95	.74	.53	—
	5300	10	5	16	DIP	H11L2-MQT-ND	.58	.49	.39	—
	7500	10.0	5	15	SOIC	H11L2M-ND	.95	.74	.53	—
	7500	10.0	5	15	SMD	H11L2SM-ND	.91	.74	.52	—
	7500	10.0	5	15	SMD	H11L2SR2MCT-ND‡	.99	.79	.55	307.36
	7500	10.0	5	15	SMD	H11L2SVM-ND‡	.91	.74	.52	—
	7500	10.0	5	15	DIP	H11L2TVM-ND‡	.91	.74	.52	—
7500	10.0	5	15	DIP	H11L2VM-ND‡	.95	.74	.53	—	
7500	60	5	16	DIP	H11L3M-ND	.95	.74	.53	—	
5300	3.2	10	16	DIP	H11N1-MQT-ND	2.41	2.13	1.38	—	
5300	10	10	16	DIP	H11N3-M-ND	2.37	2.10	1.36	—	

Fig.	Tension d'isolement	Délais de propagation max. (ns)	CMR typique V/µs	I _F (mA)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
29	2500	100	10,000	50	SMD	6N137S-ND	.95	.77	.54
	2500	100	10,000	50	SMD	HCPL0601R1CT-ND‡	3.03	2.72	1.76
	2500	100	10,000	50	SMD	HCPL0601R1TR-ND◊	1098.25/1000		
41	2500	75	10,000	5	DIP	6N137OT-ND	.95	.77	.54
	2500	75	10,000	5	DIP	HCPL2601QT-ND	1.55	1.38	.89
	2500	75	10,000	5	DIP	HCPL2611-ND	1.77	1.57	1.02
42	2500	75	10,000	5	DIP	HCPL2630QT-ND	2.88	2.56	1.65
	2500	75	10,000	5	DIP	HCPL2631QT-ND	2.24	1.99	1.29

Fig.	Tension d'isolement	BV _{CEO} minimum	tpassant/bloqué
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